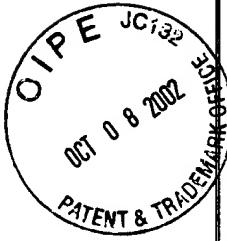


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Applicants: Christopher J. deSimone, Lucian M. Hand, Gi Jeong Kim, Seung Mo Kim, Jin An Lee
Assignee: Amkor Technology, Inc.
Title: Nonexposed Heat Sink For Semiconductor Package
Serial No.: 09/513,067 Filing Date: February 24, 2000
Examiner: C. Luu Group Art Unit: 2825
Docket No.: AB-928 US

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San Jose, California
October 8, 2002

COMMISSIONER FOR PATENTS
Washington, D. C. 20231

RESPONSE TO OFFICE ACTION

Dear Sir:

Applicants hereby respond to the Office Action that was mailed from the U.S. Patent and Trademark Office on April 8, 2002.

Thank you for the allowance of claims 37-43. Please consider the following remarks with respect to the remaining claims. An Appendix hereto provides a list of the pending claims. No amendments to the claims are made.

1. Rejection of claims 1-3, 6-7, and 10-11 under 35 USC 102

Claims 1-3, 6-7, and 10-11 stand rejected under 35 USC 102(e) as anticipated by U.S. Patent 5,929,513 to Asano et al. ("Asano"). The rejections are respectfully traversed.

Regarding claim 1, there is a recitation of both "leads" that "overhang[] a periphery of the plate" and "a plurality of electrically isolated, encapsulated members, wherein each said member extends from a perimeter of the package body toward the plate and overhangs the periphery of the plate and is in a connection with the plate." The leads and the members are distinct features of the claim.

The Examiner did not specifically identify any structure that would correspond with the "members" of claim 1. The Examiner uses the number "37", but that refers to an adhesive located only between the chip 36 and heat spreader 35. The Examiner also uses the number

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